As the pioneer in P.B.S.® brazed bonding for CMP pad conditioning disks, Abrasive Technology has set the industry standards for performance, consistency and efficiency.

**FEATURES**

- Operate on all major CMP equipment platforms in oxide (ILD, STI, POLY, BPSG) and metal (W, Cu) processes.

- Specialized manufacturing technology to control critical abrasive specifications (diamond size, shape, bond height, diamond plane), which delivers high performance.

- Ideal for both in-situ and ex-situ CMP processes to meet critical CMP process requirements.

- Available in magnetic and non-magnetic grades of stainless steel in variety of front surface configurations and sizes.

**THE P.B.S.® ADVANTAGE**

- Individually and permanently brazes diamonds in place, increasing crystal retention.

- Greater control over crystal concentration, creating a more consistent pad surface.

- Chemical bond is more durable than electroplated and protects the crystals, extending the life of each disk.
Abrasive Technology’s P.B.S.® brazed disks for CMP pad conditioning are precisely manufactured for the highest productivity in semiconductor wafer processing. Our disks are customized to operate on Oxide, Tungsten and Copper processes.

Performance:
Third party testing confirmed consistent, high-performance results on multiple disks when compared to the leading competitor.

Value:
Users achieve lower cost of ownership with AT disk:
• Improve price
• Higher quality
• Consistent performance

Customer Data: Oxide Process
Polishing Tool: Applied Materials Mirra
Polish Pad: Rohm and Haas
Slurry: Cabot